

ABSTRACT

TITLE OF THE INVENTION: LAMINATED BODY INCLUDING NOVOLAC RESIN
AS PEELING LAYER

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There is provided a laminated body for separating an object to be processed by cutting or the like, or for processing, for example, polishing a back surface of a wafer, the laminated body comprising an intermediate layer that is disposed between a support and the object to be processed and peelably adheres to the support and the object to be
10 processed, wherein the intermediate layer includes at least a peeling layer in contact with the support, and the peeling layer contains a novolac resin that absorbs light with a wavelength of 190 nm to 600 nm incident through the support, resulting in modification, and a material and a method for separation without mechanical load.

A laminated body for polishing a back surface of a wafer, the laminated body
15 comprising an intermediate layer that is disposed between a support and a circuit surface of the wafer and peelably adheres to the support and the circuit surface, wherein the intermediate layer includes an adhesion layer in contact with the wafer and a peeling layer in contact with the support, and the peeling layer contains a novolac resin that absorbs light with a wavelength of 190 nm to 600 nm incident through the support,
20 resulting in modification. The light transmittance of the peeling layer at a wavelength range of 190 nm to 600 nm may be 1 to 90%. The modification caused by absorption of light may be photodecomposition of the novolac resin.

[No figure]